L Number	Hits	Search Text	DB	Time stamp
1	0	wo-01933312-$.did.	USPAT; US-PGPUB; EPO; DERWENT	2003/07/10 16:04
2	0	wo-933312-$.did.	USPAT; US-PGPUB; EPO; DERWENT	2003/07/10 16:05
3	133	daggett.in.	USPAT; US-PGPUB; EPO; DERWENT	2003/07/10 16:17
4	65406	700/$.ccls. or 345/$.ccls.	USPAT; US-PGPUB; EPO; DERWENT	2003/07/10 16:18
5	2916	(700/$.ccls. or 345/$.ccls.) and (wafer or semiconductor same substrate)	USPAT; US-PGPUB; EPO; DERWENT	2003/07/10 16:18
6	959	((700/$.ccls. or 345/$.ccls.) and (wafer or semiconductor same substrate)) and (coat$3 or develop$4) same (wafer or substrate)	USPAT; US-PGPUB; EPO; DERWENT	2003/07/10 17:02
7	52	(((700/$.ccls. or 345/$.ccls.) and (wafer or semiconductor same substrate)) and (coat$3 or develop$4) same (wafer or substrate)) and (serial$3 or sequential$2) near3 (control$4 or regulat$3 or program$4)	USPAT; US-PGPUB; EPO; DERWENT	2003/07/10 16:21
8	2394	(700/$.ccls. or 345/$.ccls.) and (coat$3 or develop$4) same (wafer or substrate)	USPAT; US-PGPUB; EPO; DERWENT	2003/07/10 16:53
9	137147	(serial$2 or sequential$2) near3 (control$4 or regulat$3 or operat$3 or management or process$3 or execut$3)	USPAT; US-PGPUB; EPO; DERWENT	2003/07/10 17:01
10	356	((700/$.ccls. or 345/$.ccls.) and (coat$3 or develop$4) same (wafer or substrate)) and ((serial$2 or sequential$2) near3 (control$4 or regulat$3 or operat$3 or management or process$3 or execut$3))	USPAT; US-PGPUB; EPO; DERWENT	2003/07/10 16:37
11	21	(((700/$.ccls. or 345/$.ccls.) and (coat$3 or develop$4) same (wafer or substrate)) and ((serial$2 or sequential$2) near3 (control$4 or regulat$3 or operat$3 or management or process$3 or execut$3))) and interrupt$3 same (command or subroutine or subprogram or step)	USPAT; US-PGPUB; EPO; DERWENT	2003/07/10 17:02
12	11	4982694.uref.	USPAT; US-PGPUB; EPO; DERWENT	2003/07/10 16:43
13	2542	(118/$.ccls. or 396/564-641.ccls. or 134/902.ccls. or 430/$.ccls.) and (serial$2 or sequential$2) near3 (control$4 or regulat$3 or operat$3 or management or process$3 or execut$3 or program$4)	USPAT; US-PGPUB; EPO; DERWENT	2003/07/10 16:52
14	1058	((118/$.ccls. or 396/564-641.ccls. or 134/902.ccls. or 430/$.ccls.) and (serial$2 or sequential$2) near3 (control$4 or regulat$3 or operat$3 or management or process$3 or execut$3 or program$4)) and (coat$3 or develop$4) same (wafer or substrate)	USPAT; US-PGPUB; EPO; DERWENT	2003/07/10 16:53

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15	14	(((118/$.ccls. or 396/564-641.ccls. or 134/902.ccls. or 430/$.ccls.) and (serial$2 or sequential$2) near3 (control$4 or regulat$3 or operat$3 or management or process$3 or execut$3 or program$4)) and (coat$3 or develop$4) same (wafer or substrate)) and interrupt$3 same (command or subroutine or subprogram or step)	USPAT; US-PGPUB; EPO; DERWENT	2003/07/10 16:54
16	33627	(serial$2 or sequential$2) near3 (control$4 or regulat$3 or operat$3 or management or process$3 or execut$3)	EPO; JPO; DERWENT	2003/07/10 17:02
17	141	((serial$2 or sequential$2) near3 (control$4 or regulat$3 or operat$3 or management or process$3 or execut$3)) and (coat$3 or develop$4) same (wafer or substrate)	EPO; JPO; DERWENT	2003/07/10 17:02
18	1	(((serial$2 or sequential$2) near3 (control$4 or regulat$3 or operat$3 or management or process$3 or execut$3)) and (coat$3 or develop$4) same (wafer or substrate)) and interrupt$3 same (command or subroutine or subprogram or step)	EPO; JPO; DERWENT	2003/07/10 17:02